

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)							
PCN #: <b>W19</b> 1	11-02	DATE: 22-Nov-2019	MEANS OF DISTIN	NGUISHING CHA	NGED DEVICES:		
Product Affected:	: Refer to attachmen	t 2	☐ Product Mark ☐ Back Mark ☐ Date Code ■ Other		e Fab location is the 2 digit sequential te code line of the top		
Date Effective:	22-Feb-2020						
Contact:	IDT PCN DESK		Attachment:	Yes	☐ No		
E-mail: idt-pcn@lm.renesas.com		.com	Samples: Please contact your local sales representative for sample request.				
DESCRIPTION	AND PURPOSE OF O	CHANGE:					
<ul> <li>□ Die Technology</li> <li>□ Wafer Fabrication Process</li> <li>□ Assembly Process</li> <li>□ Equipment</li> <li>□ Material</li> <li>□ Testing</li> <li>■ Manufacturing Site</li> <li>□ Data Sheet</li> <li>□ Other</li> </ul>		This notification is to advise our customers that IDT has qualified TSMC Fab 6 as an alternate Foundry for the products listed on this notice.  This is to provide additional manufacturing capacity for these products.  There is no change to the product design or process technology as the existing qualified Foundry, TSMC Fab 8.  There is also no change to the package, backend manufacturing process or the the data sheet.  Refer to page 2 for the qualification report.					
		ualification to date and chara	acterization tests, then	re is no change to the	ne performance or		
IDT records indi to grant approval it will be assume IDT reserves the	l or request additional in d that this change is acc	ritten notification of this chanformation. If IDT does not ceptable.	receive acknowledge	ment within 30 day	s of this notice		
Customer:			Approval for s	shipments prior	to effective date.		
Name/Date:		E-	Mail Address:				
Title:		Pł	none# /Fax# :				
CUSTOMER CO			_				
	_						
IDT ACKNOWI	LEDGMENT OF REC	CEIPT:					
RECD. BY:			DATE:				



## **Qualification Report**

**Product Type:** IDTP9242 (Wireless Power Transmitter)

**Device Family:** AW670T **Process Technology:** CM018BCD, 1P4M

Package Type:NDG40 (QFN)Fab Location:TSMC, Taiwan

Test Description	Conditions	Sample Size	Reject	Comments
Device Characterization	IDT's datasheet condition	35	0	Pass
High Temperature Operating Life (Dynamic)	JESD22-A108, +125°C, Vcc-max	77 x 3 lots	0	Pass
ESD: Human Body Model	JESD22-A114 (JS-001) Classification (1C, 2KV)	3	0	Pass
ESD: Charged Device Model	JESD22-C101 Classification (C1, 500V)	3	0	Pass
Latch-Up	JESD78	3	0	Pass
High Temperature Storage Life	JESD22-A103, +150°C	25 x 3 lots	0	Pass
Highly Accelerated Temperature and Humidity Stress (Biased)	JESD22-A110, +130°C, 85% R.H., 100 hrs	25 x 3 lots	0	QBS by P12-04-08
Temperature Cycling	JESD22-A104-B (Cond. B -55°C to 125°C)	77 x 3 lots	0	QBS by P12-04-08



## PRODUCT/PROCESS CHANGE NOTICE (PCN)

## **ATTACHMENT 2 - PCN # : W1911-02**

## **Affected Part Numbers**

Part Number	Part Number	Part Number	Part Number
P9241-G0NDGI	P9242-G0NDGI	P9242-G6NDGI	P9242-GNDGI
P9241-G0NDGI8	P9242-G0NDGI8	P9242-G6NDGI8	P9242-GNDGI8
P9241-G1NDGI	P9242-G1NDGI	P9242-G7NDGI	P9243-G1NDGI
P9241-G1NDGI8	P9242-G1NDGI8	P9242-G7NDGI8	P9243-G1NDGI8
P9241-GB1NDGI	P9242-G2NDGI	P9242-G8NDGI	P9243-GBNDGI
P9241-GB1NDGI8	P9242-G2NDGI8	P9242-G8NDGI8	P9243-GBNDGI8
P9241-GBNDGI	P9242-G3NDGI	P9242-G9NDGI	P9243-G-EVK
P9241-GBNDGI8	P9242-G3NDGI8	P9242-G9NDGI8	P9243-G-EVKSMP
P9241-G-EVK	P9242-G4NDGI	P9242-GBNDGI	P9243-GNDGI
P9241-G-EVKSMP	P9242-G4NDGI8	P9242-GBNDGI8	P9243-GNDGI8
P9241-GNDGI	P9242-G5NDGI	P9242-G-EVK	
P9241-GNDGI8	P9242-G5NDGI8	P9242-G-EVKSMP	